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Application No. 09/939,804
Reply to Office Action of July 17, 2003

## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listings of claims in the application:

Claims 1-2 (Canceled).

Claim 3 (Currently Amended) A floor polishing composition, comprising: containing a film-formable organic resin material as the main component, which further contains and

at least scaly particles,

wherein the <u>said</u> scaly particles are silica corresponding to layered polysilicic acid, wherein the <u>said</u> layered polysilicic acid is scaly silica particles having <u>has layered</u> particle structures of layered structures that are present independently to <u>from</u> each other,

which wherein said layered polysilicic acid comprises foliar silica secondary particles that are present discretely from each other,

wherein a plurality of flaky primary particles of scaly silica are overlaid one on another and aligned face-to-face in parallel with one another, and

wherein the foliar silica secondary particles are obtainable obtained by disintegrating an aqueous slurry of layer-like polysilicic acid or layer-like polysilicic salt tertiary agglomerated particles of silica by means of a mechanical high speed stirring system employing a disintegrating medium.

Claim 4 (Canceled).

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Claim 5 (Original): The floor polishing composition according to Claim 3, wherein the foliar silica secondary particles composing the scaly silica are silica having the main peaks corresponding to silica-X and/or silica-Y according to X-ray diffraction analysis.

Claim 6-7 (Canceled).

Claim 8 (Previously Presented): The floor polishing composition according to Claim 3, wherein the organic resin material in the floor polishing composition is an organic resin material in aqueous emulsion state.

Claim 9 (Canceled).

Claim 10 (Previously Presented): The floor polishing composition according to Claim 5, wherein the organic resin material in the floor polishing composition is an organic resin material in aqueous emulsion state.

Claim 11 (Previously Presented): A floor polishing film comprising a film-formable Conganic resin material provided on a surface of a substrate, which resin material contains scaly particles.

Claim 12 (Original): The floor polishing film according to Claim 11, wherein the scaly particles are silica corresponding to layered polysilicic acid.

Claim 13 (Original): The floor polishing film according to Claim 12, wherein the layered polysilicic acid is scaly silica particles having particle structures of layered structures

present independently to each other, which comprises foliar silica secondary particles
wherein a plurality of flaky primary particles of scaly silica are overlaid one on another and
aligned face-to-face in parallel with one another.

Claim 14 (Original): The floor polishing film according to Claim 12, wherein the foliar silica secondary particles composing scaly silica in the film are silica having the main peaks corresponding to silica-X and/or silica-Y according to x-ray diffraction analysis.

Claim 15 (Original): The floor polishing film according to Claim 13, wherein the foliar silica secondary particles composing scaly silica in the film are silica having the main peaks corresponding to silica-X and/or silica-Y according to X-ray diffraction analysis.

Claim 16 (Previously Presented): A floor polishing film according to Claim 11, wherein an overcoating layer comprising an organic resin material is provided on the floor polishing film.

Claim 17 (Previously Presented): A floor polishing film according to Claim 12, wherein an overcoating layer comprising an organic resin material is provided on the floor polishing film.

Claim 18 (Previously Presented): A floor polishing film according to Claim 13, wherein an overcoating layer comprising an organic resin material is provided on the floor polishing film.

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Claim 19 (Previously Presented): A floor polishing film according to Claim 14, wherein an overcoating layer comprising an organic resin material is provided on the floor polishing film.

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Claim 20 (Previously Presented): A floor polishing film according to Claim 15, wherein an overcoating layer comprising an organic resin material is provided on the floor polishing film.

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Claim 21 (Previously Presented): A method of treating a floor comprising applying a floor polishing composition containing a film-formable organic resin material as the main component, which further contains at least scaly particles, to the floor.

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Claim 22 (Previously Presented): The method according to Claim 21, wherein the scaly particles are silica corresponding to layered polysilicic acid.

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Claim 23 (Previously Presented): A method of treating a floor comprising applying the floor polishing composition of Claim 3 to the floor.

Claim 24 (Previously Presented): A method of treating a floor comprising applying the floor polishing composition of Claim 5 to the floor.

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Claim 25 (Previously Presented): A method of treating a floor comprising applying the floor polishing composition of Claim 8 to the floor.

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Claim 26 (Previously Presented): A method of treating a floor comprising applying the floor polishing composition of Claim 10 to the floor.

Claim 27 (New): A floor polishing film according to Claim 11, wherein said scaly particles are silica corresponding to layered polysilicic acid,

wherein said layered polysilicic acid has layered particle structures that are present independently from each other,

wherein said layered polysilicic acid comprises foliar silica secondary particles that are present discretely from each other,

wherein a plurality of flaky primary particles of scaly silica are overlaid one on another and aligned face-to-face in parallel with one another, and

wherein the foliar silica secondary particles are obtained by disintegrating an aqueous slurry of tertiary agglomerated particles of silica by means of a mechanical high speed stirring system employing a disintegrating medium.

## **BASIS FOR THE AMENDMENT**

Claim 3 has been amended as supported at page 14, line 10 to page 15, line 4; at page 17, 1<sup>st</sup> full paragraph; at page 18, lines 14-22, at page 19, line 25 to page 20, line 1 and at page 28, lines 1 and 2.

New Claim 27 has been added as supported at page 14, line 10 to page 15, line 4; at page 17, 1<sup>st</sup> full paragraph; at page 18, lines 14-22, at page 19, line 25 to page 20, line 1 and at page 28, lines 1 and 2.

No new matter is believed to have been added by entry of this amendment. Entry and favorable reconsideration are respectfully requested.

Upon entry of this amendment Claims 3, 5, 8 and 10-27 will now be active in this application.

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## **INTERVIEW SUMMARY**

Applicants wish to thank Examiner Uhlir for the helpful and courteous discussion with Applicants' Representative on September 3, 2003. During this discussion it was noted that one difference appears to be that the scaly silica primary particles of <u>Terase et al</u> are <u>randomly</u> stacked whereas the flaky primary particles of scaly silica are overlaid and aligned face to face in parallel.